

ABSTRACT

5 **Integrated circuit device, electronic unit for smart cards using said device and method of manufacturing said device**

This invention relates to an integrated circuit device, in particular for manufacturing smart card electronic units for smart cards. It comprises:

10 an active layer (32) including a semiconductor material within which integrated circuits are formed and having a face (34) provided with a plurality of electrical connection terminals (36) and a second face, wherein said face has a thickness smaller

15 than 100 μm , and

20 a complementary layer (40) having a first face (42) attached to the active face of the active layer, a second face (44) and a side surface (48), wherein said complementary layer includes a plurality of recesses (46), each recess extending through the whole thickness of the complementary layer, and extending from a contact terminal (36) to said side surface (48).

25 Figure 2A